## JK-SMD300L-24 PPTC DEVICES Part Number: Q/JKTD-24-300



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Terminal pad materials :Tin-Plated Nickle-copper

Terminal pad solderability : Meets EIA specification RS 186-9E and ANSI/J-STD-002 Category 3.

Marking : JK300L=2920(300)

Table1 :DIMENTION	(Unit : mm)
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Model Marking	А		В		С		D	
Widdei	Model Marking	Min.	Max.	Min.	Max.	Min.	Max	Min.
JK-SMD300L-24	JK300L	6.73	7.98	4.80	5.44	0.50	1.20	0.30

### Table2 :PERFORMANCE RATINGS:

Model V <sub>max</sub> (Vdc)	V <sub>max</sub> I <sub>max</sub>	I <sub>max</sub>	Ihold	I <sub>trip</sub>	P <sub>d</sub>	Maximum Time To Trip		Resistance		
	(A)	@25°C @ (A)	@25°C (A)	Typ (W)	Current	Time	Ri <sub>min</sub>	Ri <sub>typ</sub>	R1 <sub>max</sub>	
					(A)	(Sec)	$(\Omega)$	$(\Omega)$	$(\Omega)$	
JK-SMD300L-24	24.0	40	3.0	6.00	1.500	8.00	20.0	0.012	0.017	0.056

### Table3:Test Conditons and Standards

Item	Test Conditon	Standard
Initial Resistance	25°C	$0.012{\sim}0.056\Omega$
I <sub>H</sub>	25°C, 3.00A, 60min	No Trip
Ttrip	25°C, 8.00A	≤20.0s
Trip endurance	24V, 401hr	No arcing or burning

Operating Temperature: -40℃ TO 85℃ Packaging: Bulk,1500pcs per bag

SHENZHEN JINRUI ELECTRONIC MATERIAL CO.,LTD6 F DISTRICT NO. 300INDUSTRY PARKSHANGKENG COMMUNITY GUANLAN STREET BAOAN SHENZHENTEL:0755-2654632726584158FAX:0755-

6 F DISTRICT NO. 3000046 BLDG Hi-Tech SCIENCE & EET BAOAN SHENZHEN

FAX: 0755-26546562

Web Site: <u>www.jkpptc.com</u>

E-mail:customer@jkpptc.com

#### JK-SMD300L-24 PPTC DEVICES Edition: A0 Part Number: Q/JKTD-24-300 Page No: 2 OF 3 Solder reflow conditions tp Critical Zone Tp Ramp up-F, to Tp T lemperature TSMAX TS<sub>MIN</sub> ts Ramp down Preheat 25 t 25°C to Peak Time = **Reflow Profile Profile Feature Pb-Free Assembly** Average ramp up rate (Ts<sub>MAX</sub> to Tp) • Recommended reflow methods: IR, vapor phase 3°C/second max. Preheat oven, hot air oven, N2 environment for lead-free. • Temperature min. (Ts<sub>MIN</sub>) 150°C • Devices are not designed to be wave soldered to 200°C Temperature max. (Ts<sub>MAX</sub>) the bottom side of the board. Time (ts<sub>MIN</sub> to ts<sub>MAX</sub>) 60-120 seconds Time maintained above: • Recommended maximum paste thickness is 217°C • Temperature (T<sub>1</sub>) 0.25mm (0.010inch). • Time (t<sub>L</sub>) 60-150 seconds • Devices can be cleaned using standard industry Peak/Classification temperature (Tp) 260°C Time within 5°C of actual peak temperature methods and solvents. Time (tp) 30 seconds max. • Soldering temprature profile meets RoHs leadfree Ramp down rate 3°C/second max. process. Time 25°C to peak temperature 8 minutes max. Note: All temperatures refer to topside of the package, measured on the package body surface Notes: If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements

SHENZHEN JINRUI ELECTRONIC MATERIAL CO.,LTD6 F DISTRICT NO. 3000046 BLDG Hi-Tech SCIENCE &INDUSTRY PARKSHANGKENG COMMUNITY GUANLAN STREET BAOAN SHENZHENTEL:0755-2654632726584158Web Site:www.jkpptc.comE-mail:customer@jkpptc.com

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### Solder reflow conditions

### Storage

The maximum ambient temperature shall not exceed  $38 \,^{\circ}$ C. Storage temperatures higher than  $38 \,^{\circ}$ C could result in the deformation of packaging materials. The maximum relative humidity recommended for storage is 60%. High humidity with high temperature can accelerate the oxidation of the solder plating on the termination and reduce the solderability of the components. Sealed plastic bags with desiccant shall be used to reduce the oxidation of the termination and shall only be opened prior to use. The products shall not be stored in areas where harmful gases containing sulfur or chlorine are present

### WARNING

 $\cdot$  Use PPTC beyond the maximum ratings or improper use may result in device damage and possible electrical arcing and flame.

 $\cdot$  PPTC are intended for protection against occasional over current or over temperature fault conditions and should not be used when repeated fault conditions or prolonged trip events are anticipated.

• Device performance can be impacted negatively if devices are handled in a manner inconsistent with recommended electronic, thermal, and mechanical procedures for electronic components.

• Use PPTC with a large inductance in circuit will generate a circuit voltage (L di/dt) above the rated voltage of the PPTC.

· Avoid impact PPTC device its thermal expansion like placed under pressure or installed in limited space.

 $\cdot$  Contamination of the PPTC material with certain silicon based oils or some aggressive solvents can adversely impact the performance of the devices.PPTC SMD can be cleaned by standard methods.

 $\cdot$  Requests that customers comply with our recommended solder pad layouts and recommended reflow profile. Improper board layouts or reflow profilecould negatively impact solderability performance of our devices.

SHENZHEN JINRUI ELECTRONIC MATERIAL CO.,LTD	6 F DISTRICT NO. 3000046 BLDG Hi-Tech SCIENCE &				
INDUSTRY PARK SHANGKENG COMMUNITY GUANLAN STREET BAOAN SHENZHEN					
TEL: 0755-26546327 26584158	FAX: 0755-26546562				
Web Site: <u>www.jkpptc.com</u>	E-mail:customer@jkpptc.com				

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